



CyberOptics Unveils New Dual-mode MRS™ Sensor for Solder Paste Inspection at IPC APEX 2022

Minneapolis, Minnesota — January 19, 2022 — [CyberOptics® Corporation](#) (NASDAQ: CYBE), a leading global developer and manufacturer of high-precision 3D sensing technology solutions will unveil the new Dual-Mode MRS sensor for the SE3000™ SPI system in Booth #2541 at the 2022 IPC APEX EXPO, Jan. 25-27, 2022 at the San Diego Convention Center in California. The company will also demonstrate the SQ3000™ Multi-Function system for AOI, SPI and CMM and feature the new SQ3000+ Multi-Function system for advanced applications.

The new Dual-Mode MRS sensor for the [SE3000™ SPI system](#) provides maximum flexibility for dedicated solder paste inspection applications, with one mode for high speed inspection and another mode for high resolution inspection. The new sensor is an extension of the proprietary Multi-Reflection Suppression™ sensor portfolio that provides industry-leading performance in semiconductor and SMT markets. The SE3000 is ideal for measuring height, area, volume, registration and bridging, as well as detecting insufficient paste, excess height, smear, offset and more.



“We designed the Dual-Mode MRS sensor specifically for our SE3000 system to provide both superior performance and versatility for SPI,” said Dr. Subodh Kulkarni, President and CEO, CyberOptics, “We’re providing yet another solution that can significantly improve our customers’ yields, processes and productivity.”

At APEX, the company will also feature the [SQ3000™+ Multi-Function system](#) for inspection and metrology, an extension of the multi-award-winning SQ3000 platform deemed best-in-class, that not only conducts AOI and SPI, but uniquely delivers in-line, full coordinate measurement (CMM) data in seconds, not hours. The all-in-one system offers a combination of unmatched high accuracy and high speed, with an even higher resolution MRS sensor that inhibits reflection-based distortions caused by shiny components and surfaces.

The SQ3000+ is specifically designed for high-end applications including advanced packaging, mini-LED, advanced SMT for medical, military, aerospace and advanced electronics, 008004/0201 SPI, socket metrology and other challenging CMM applications.



For more information, visit www.cyberoptics.com.

About CyberOptics

CyberOptics Corporation (www.cyberoptics.com) is a leading global developer and manufacturer of high-precision 3D sensing technology solutions. CyberOptics' sensors are used for inspection and metrology in the SMT and semiconductor markets to significantly improve yields and productivity. By leveraging its leading-edge technologies, the Company has strategically established itself as a global leader in high precision 3D sensors, allowing CyberOptics to further increase its penetration of key vertical markets. Headquartered in Minneapolis, Minnesota, CyberOptics conducts worldwide operations through its facilities in North America, Asia and Europe.

Statements regarding the Company's anticipated performance are forward-looking and therefore involve risks and uncertainties, including but not limited to: a possible worldwide recession or depression resulting from the economic consequences of the COVID-19 pandemic; the negative effect on our revenue and operating results of the COVID-19 crisis on our customers and suppliers and the global supply chain; market conditions in the global SMT and semiconductor capital equipment industries; trade relations between the United States and China and other countries; the timing of orders and shipments of our products, particularly our 3D MRS SQ3000 Multi-Function systems and MX systems for memory module inspection; increasing price competition and price pressure on our product sales, particularly our SMT systems; the level of orders from our OEM customers; the availability of parts required to meet customer orders; unanticipated product development challenges; the effect of world events on our sales, the majority of which are from foreign customers; rapid changes in technology in the electronics and semiconductor markets; product introductions and pricing by our competitors; the success of our 3D technology initiatives; the market acceptance of our SQ3000 Multi-Function systems and products for semiconductor inspection and metrology; costly and time consuming litigation with third parties related to intellectual property infringement; the negative impact on our customers and suppliers due to past and future terrorist threats and attacks and any acts of war; the impact of the MX3000 orders on our consolidated gross margin percentage in any future period; risks related to cancellation or renegotiation of orders we have received; and other factors set forth in the Company's filings with the Securities and Exchange Commission.

For additional information, contact:

Carla Furanna
Vice President of Global Marketing
952-820-5837